



### General Description

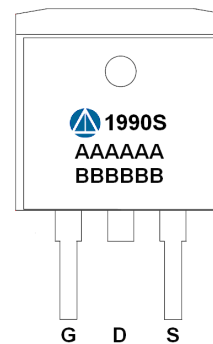
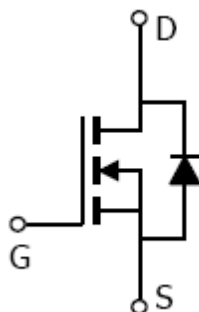
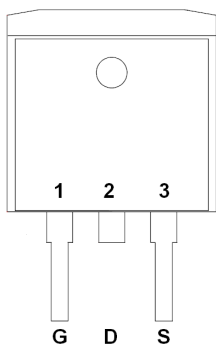
AFN1990S, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

### Features

- 60V/40A,  $R_{DS(ON)} = 7.8m\Omega @ V_{GS} = 10V$
- 60V/25A,  $R_{DS(ON)} = 9.8m\Omega @ V_{GS} = 6V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- TO-263-2L package design

### Pin Description ( TO-263-2L )



### Application

- Synchronous Rectifier
- Power Supplies

### Pin Define

Pin	Symbol	Description
1	G	Gate
2	D	Drain
3	S	Source

### Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN1990ST263RG	1990S AAAAAA BBBBBB	TO-263-2L	Tape & Reel	800 EA

- ※ A Lot code
- ※ B Date code
- ※ AFN1990ST220TG : Tube ; Pb- Free ; Halogen –Free



### Absolute Maximum Ratings

(T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	60	V
Gate-Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current(T <sub>J</sub> =150°C)	I <sub>D</sub>	T <sub>C</sub> =25°C	60
		T <sub>C</sub> =70°C	40
Pulsed Drain Current	I <sub>DM</sub>	150	A
Continuous Source Current(Diode Conduction)	I <sub>S</sub>	80	
Single Pulse Avalanche Current	I <sub>AS</sub>	40	
Power Dissipation	P <sub>D</sub>	T <sub>C</sub> =25°C	100
		T <sub>A</sub> =25°C	3.1
Operating Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature Range	T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient	R <sub>θJA</sub>	62.5	°C/W

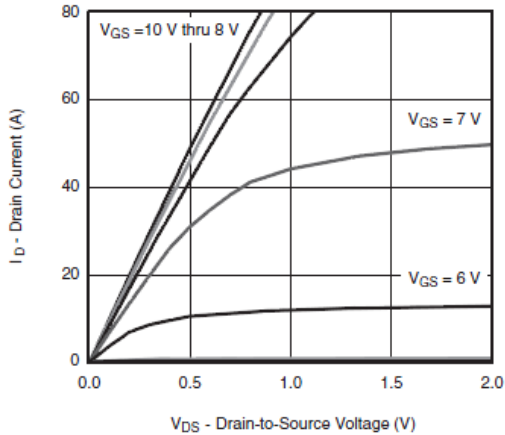
### Electrical Characteristics

(T<sub>A</sub>=25°C Unless otherwise noted)

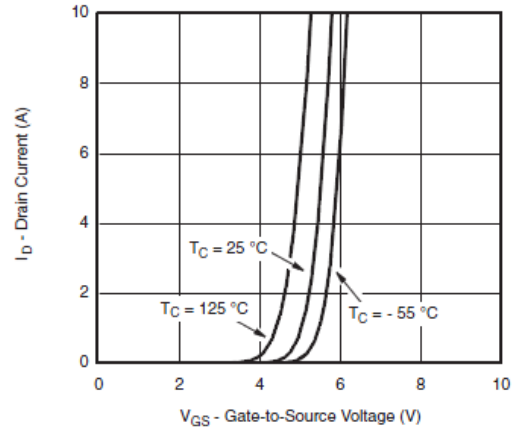
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0		4.0	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =48V, V <sub>GS</sub> =0V			1	μA
		V <sub>DS</sub> =48V, V <sub>GS</sub> =0V T <sub>J</sub> =85°C			30	
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 10V, V <sub>GS</sub> =10V	80			A
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =40A		6.3	7.8	mΩ
		V <sub>GS</sub> =6V, I <sub>D</sub> =25A		8	9.8	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =15A		38		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =40A, V <sub>GS</sub> =0V		0.8	1.3	V
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V I <sub>D</sub> ≅20A		35	60	nC
Gate-Source Charge	Q <sub>gs</sub>			12		
Gate-Drain Charge	Q <sub>gd</sub>			10		
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V f=1MHz		2080		pF
Output Capacitance	C <sub>oss</sub>			320		
Reverse Transfer Capacitance	C <sub>rss</sub>			120		
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V, R <sub>L</sub> =1.53Ω I <sub>D</sub> ≅20A, V <sub>GEN</sub> =10V R <sub>G</sub> =1.0Ω		10	20	ns
	t <sub>r</sub>			10	20	
Turn-Off Time	t <sub>d(off)</sub>			15	30	
	t <sub>f</sub>			10	20	



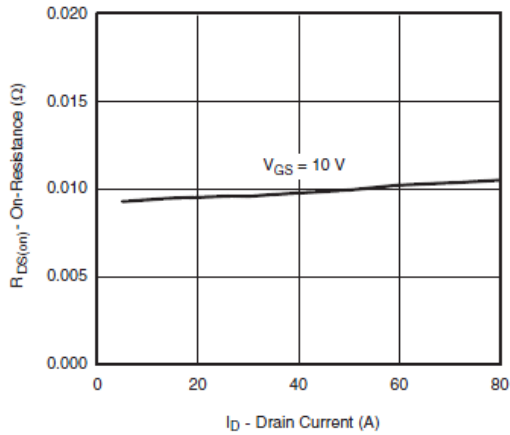
## Typical Characteristics



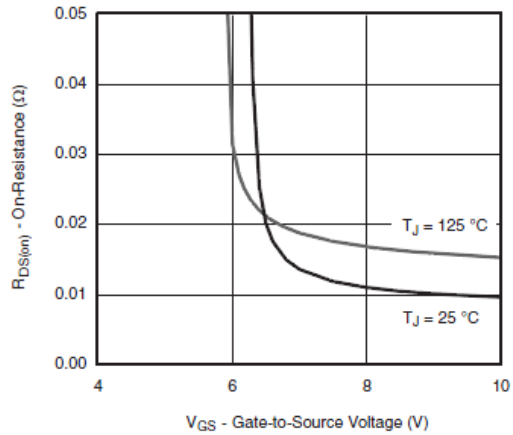
Output Characteristics



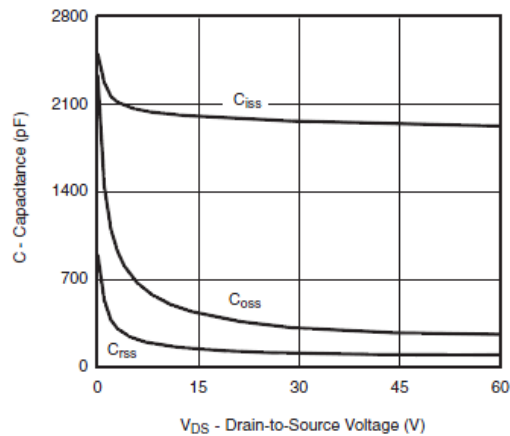
Transfer Characteristics



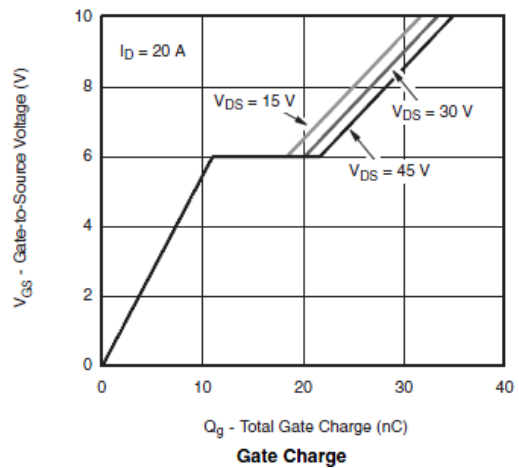
On-Resistance vs. Drain Current



On-resistance vs. Gate-to-Source Voltage



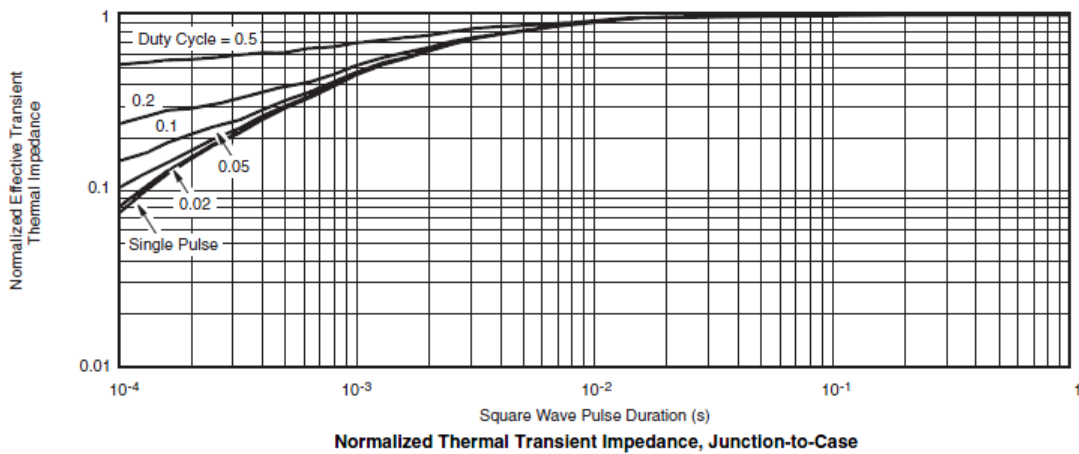
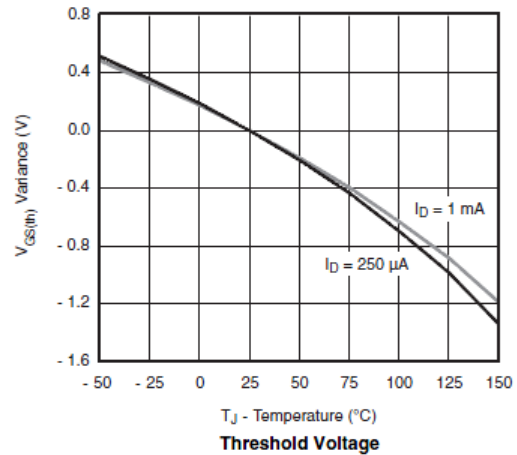
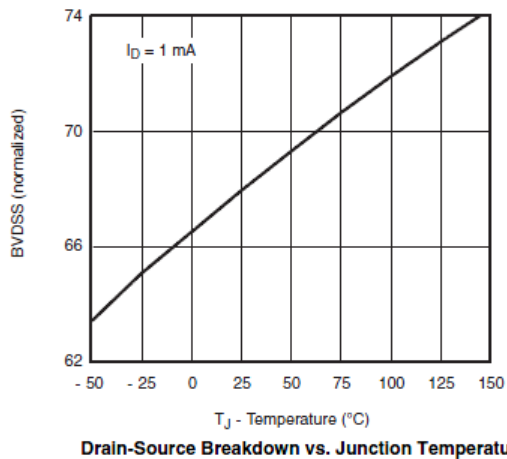
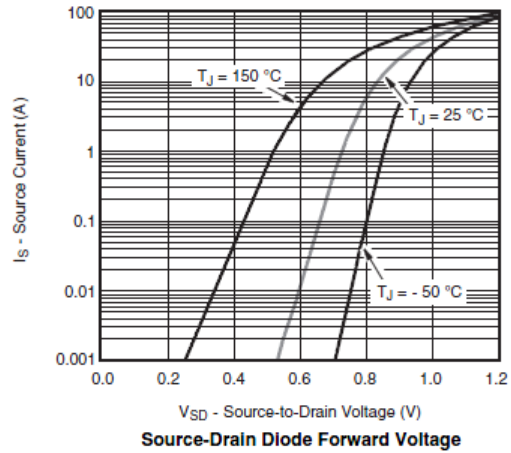
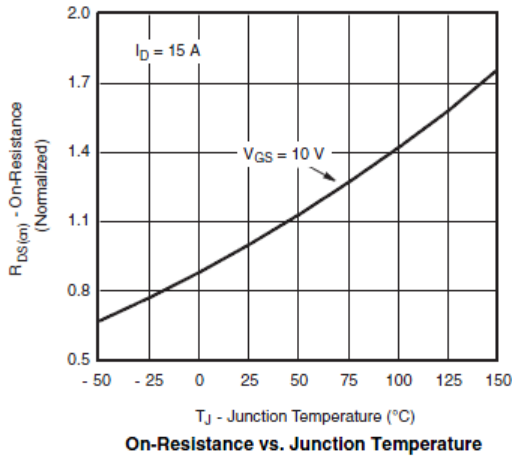
Capacitance



Gate Charge



## Typical Characteristics





## Typical Characteristics

Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



